



Date Created: 1/9/2004
Date Issued: 1/19/2004
PCN # 20040202

FORECAST CHANGE NOTIFICATION

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence. This is a preliminary notification. A final PCN will be issued when qualification is complete and data is available.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

If you have any questions concerning this change, please contact:

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PCN Originator

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REL Engineer

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PCN Type: Alternate Assembly/Test Location/Qualification

Effectivity

Expected 1st Device Shipment Date: 4/25/2004
Earliest Year/Work Week of Changed Product: 0418
(Note: Package marking may differ from this format)

Product ID (Description):

Description of Change:

Fairchild Semiconductor initial offerings in this package were manufactured at Amkor Technologies (Phillipines) which is a Fairchild qualified sub-contractor. This change is to allow manufacturing of TSSOP28L at the Fairchild Semiconductor Penang assembly facility. The intent is to ultimately offer Fairchild TSSOP28L products manufactured at both the Fairchild Semiconductor Penang site and Amkor Technologies (Phillipines) and to ship the units from all locations interchangeably to better serve our customers.

The FSPMbill of material (BOM) will be as follows:

Leadframe base: Copper C194
Internal lead plating: SPot silver
Die-Attach paste: Hitachi Poly 6, conductive, silver filled
Gold wire: 99.99%
Mold compound: Shinetsu KMC289-7
Lead finish: Post plated, Pb(15%)/Sn(85%)

Effect of Change:

There is no change to the physical dimensions of the package. Both the assembly locations are assembling to exactly the same marketing outline. There will be no change to the quality or reliability of this package.

Qualification:

The qualification vehicle shall be 3 lots of FAN5019MTC processed with 3 different batches of materials.

Reliability stress testing will be performed to qualify the Fairchild Penang plant as outlined in the qualification plan attached. Final PCN will be issued upon completion of full reliability testing.

Qual/REL Plan Numbers

Qual Plan: Q20030165

From: cpmtep Date: 8/26/2003 Qual Plan: Q20030165

Requestor of Qualification: Fei Tan

Device: FAN5019MTC

Product Line: 02FR01 Product Family Code: 96

Stress Test	High Temp	Low Temp	% Hum	PSI	Spl A	Spl B	Spl C	Spl D	TPT Dura
TMCL	150	-65			80	80	80	80	500
THBT	85		85		80	80	80	80	1000
SOPL	150				80	80	80	80	168
HTSL	150				80	80	80	80	1000
ACLV	121		100	15	80	80	80	80	168
TOTAL					400	400	400	400	1000
									96
									336

Affected FSIDs

FAN5018MTC	FAN5018MTCX	FAN5019MTC
FAN5019MTCX	FAN5026MTC	FAN5026MTCX
FAN5092MTC	FAN5092MTCX	FAN5094MTC
FAN5094MTCX	FAN5095MTC	FAN5231MTC
FAN5236MTC	FAN5236MTCX	FAN5239MTC
FAN5240MTC	FAN5240MTCX	FAN5243MTC
FAN5244MTC	FAN53166MTCX	FAN53168MTCX
FAN53180MTCX	FAN53181MTCX	